

Product Change Notification - KSRA-10EBTH043

Date:

16 Mar 2020

Product Category:

Power MOSFET Drivers

Affected CPNs:

7

Notification subject:

CCB 3677 Final Notice: Qualification of MTAI as a new assembly site for Micrel MIC4609YWM device family available in 28L SOIC package using 160x205 mils lead frame paddle size.

Notification text:

PCN Status:

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as a new assembly site for Micrel MIC4609YWM device family available in 28L SOIC package using 160x205 mils lead frame paddle size.

Pre Change:

Assembled at ANAP assembly site using 8290 die attach material, G700LS molding compound material and 150 x200 mils lead frame paddle size

Post Change:

Assembled at MTAI assembly site using 3280 die attach material, G600 molding compound material and 160x205 mils lead frame paddle size

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Amkor Technology Philippine (P1/P2), INC. / ANAP	Microchip Technology Thailand (HQ) / MTAI				
Wire material	Au	Au				
Die attach material	8290	3280				
Molding compound material	G700LS	G600				
Lead frame material	CDA194	CDA194				
Lead Frame Paddle Size	150 x200 mils	160x205 mils				

Impacts to Data Sheet:

None

Change Impact: None Reason for Change: To improve productivity by qualifying MTAI as new assembly site Change Implementation Status: In Progress



Estimated First Ship Date

April 16, 2020(date code: 2016)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2019					March 2020			April 2020						
Workweek	05	06	07	08	09	>	10	11	12	13	14	15	16	17	18
Initial PCN Issue			V												
Date			^												
Qual Report									Х						
Availability									^						
Final PCN Issue									Х						
Date									^						
Estimated															
Implementation													Х		
Date															

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

February 13, 2019: Issued initial notification.

March 16, 2020: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on April 16, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-10EBTH043_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. KSRA-10EBTH043 - CCB 3677 Final Notice: Qualification of MTAI as a new assembly site for Micrel MIC4609YWM device family available in 28L SOIC package using 160x205 mils lead frame paddle size.

Affected Catalog Part Numbers (CPN)

MIC4609YWM MIC4609YWM-TR